

# DATA SHEET

**74ABT2952**

**Octal registered transceiver (3-State)**

Product specification  
Supersedes data of 1995 Jun 15  
IC23 Data Handbook

1998 Feb 11

## Octal registered transceiver (3-State)

## 74ABT2952

## FEATURES

- 8-bit registered transceiver
- Independent registers for A and B buses
- Output capability: +64mA/−32mA
- Latch-up protection exceeds 500mA per JEDEC Std 17
- ESD protection exceeds 2000V per MIL STD 883 Method 3015 and 200V per Machine Model
- Power-up 3-State
- Power-up reset
- Live insertion/extraction permitted

## DESCRIPTION

The 74ABT2952 high-performance BiCMOS device combines low static and dynamic power dissipation with high speed and high output drive.

The 74ABT2952 device is an 8-bit registered transceiver. Two 8-bit back-to-back registers store data flowing in both directions between two bidirectional buses. Data applied to the inputs is entered and stored on the rising edge of the Clock (CPXX) provided that the Clock Enable ( $\overline{\text{CEXX}}$ ) is Low. The data is then present at the 3-State output buffers, but is only accessible when the Output Enable ( $\overline{\text{OEXX}}$ ) is Low. Data flow from A inputs to B outputs is the same as for B inputs to A outputs.

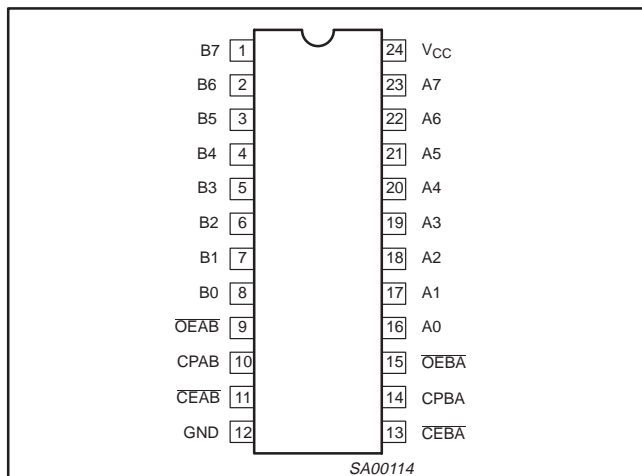
## QUICK REFERENCE DATA

SYMBOL	PARAMETER	CONDITIONS $T_{\text{amb}} = 25^{\circ}\text{C}; \text{GND} = 0\text{V}$	TYPICAL	UNIT
$t_{\text{PLH}}$ $t_{\text{PHL}}$	Propagation delay CPBA to An or CPAB to Bn	$C_L = 50\text{pF}; V_{\text{CC}} = 5\text{V}$	5.7	ns
$C_{\text{IN}}$	Input capacitance	$V_I = 0\text{V}$ or $V_{\text{CC}}$	4	pF
$C_{\text{I/O}}$	I/O capacitance	Outputs disabled; $V_O = 0\text{V}$ or $V_{\text{CC}}$	7	pF
$I_{\text{CCZ}}$	Total supply current	Outputs disabled; $V_{\text{CC}} = 5.5\text{V}$	110	$\mu\text{A}$

## ORDERING INFORMATION

PACKAGES	TEMPERATURE RANGE	OUTSIDE NORTH AMERICA	NORTH AMERICA	DWG NUMBER
24-Pin Plastic DIP	−40°C to +85°C	74ABT2952 N	74ABT2952 N	SOT222-1
24-Pin plastic SO	−40°C to +85°C	74ABT2952 D	74ABT2952 D	SOT137-1
24-Pin Plastic SSOP Type II	−40°C to +85°C	74ABT2952 DB	74ABT2952 DB	SOT340-1
24-Pin Plastic TSSOP Type I	−40°C to +85°C	74ABT2952 PW	74ABT2952PW DH	SOT355-1

## PIN CONFIGURATION



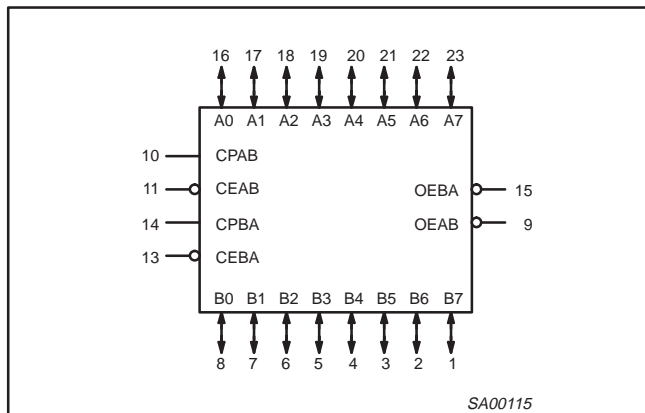
## PIN DESCRIPTION

PIN NUMBER	SYMBOL	NAME AND FUNCTION
10, 14	CPAB / CPBA	Clock input A to B / Clock input B to A
11, 13	$\overline{\text{CEAB}}$ / $\overline{\text{CEBA}}$	Clock enable input A to B / Clock enable input B to A
16, 17, 18, 19, 20, 21, 22, 23	A0 – A7	Data inputs/outputs (A side)
1, 2, 3, 4, 5, 6, 7, 8	B0 – B7	Data outputs/outputs (B side)
9, 15	$\overline{\text{OEAB}}$ / $\overline{\text{OEBA}}$	Output enable inputs
12	GND	Ground (0V)
24	$V_{\text{CC}}$	Positive supply voltage

# Octal registered transceiver (3-State)

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## LOGIC SYMBOL



## FUNCTION TABLE for Register An or Bn

INPUTS			INTERNAL Q	OPERATING MODE
An or Bn	CPXX	CEXX		
X	X	H	NC	Hold data
L H	↑ ↑	L L	L H	Load data

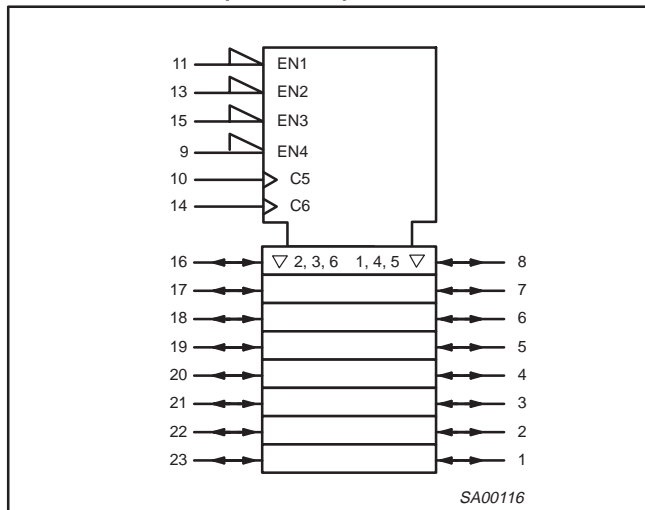
H = High voltage level  
 L = Low voltage level  
 ↑ = Low-to-High transition  
 X = Don't care  
 XX = AB or BA  
 NC = No change

## FUNCTION TABLE for Output Enable

INPUTS	INTERNAL Q	An or Bn OUTPUTS	OPERATING MODE
OE <sub>XX</sub>			
H	X	Z	Disable outputs
L L	L H	L H	Enable outputs

H = High voltage level  
 L = Low voltage level  
 X = Don't care  
 XX = AB or BA  
 Z = High impedance "off" state

## LOGIC SYMBOL (IEEE/IEC)



## ABSOLUTE MAXIMUM RATINGS<sup>1, 2</sup>

SYMBOL	PARAMETER	CONDITIONS	RATING	UNIT
V <sub>CC</sub>	DC supply voltage		-0.5 to +7.0	V
I <sub>IK</sub>	DC input diode current	V <sub>I</sub> < 0	-18	mA
V <sub>I</sub>	DC input voltage <sup>3</sup>		-1.2 to +7.0	V
I <sub>OK</sub>	DC output diode current	V <sub>O</sub> < 0	-50	mA
V <sub>OUT</sub>	DC output voltage <sup>3</sup>	output in Off or High state	-0.5 to +5.5	V
I <sub>OUT</sub>	DC output current	output in Low state	128	mA
T <sub>stg</sub>	Storage temperature range		-65 to 150	°C

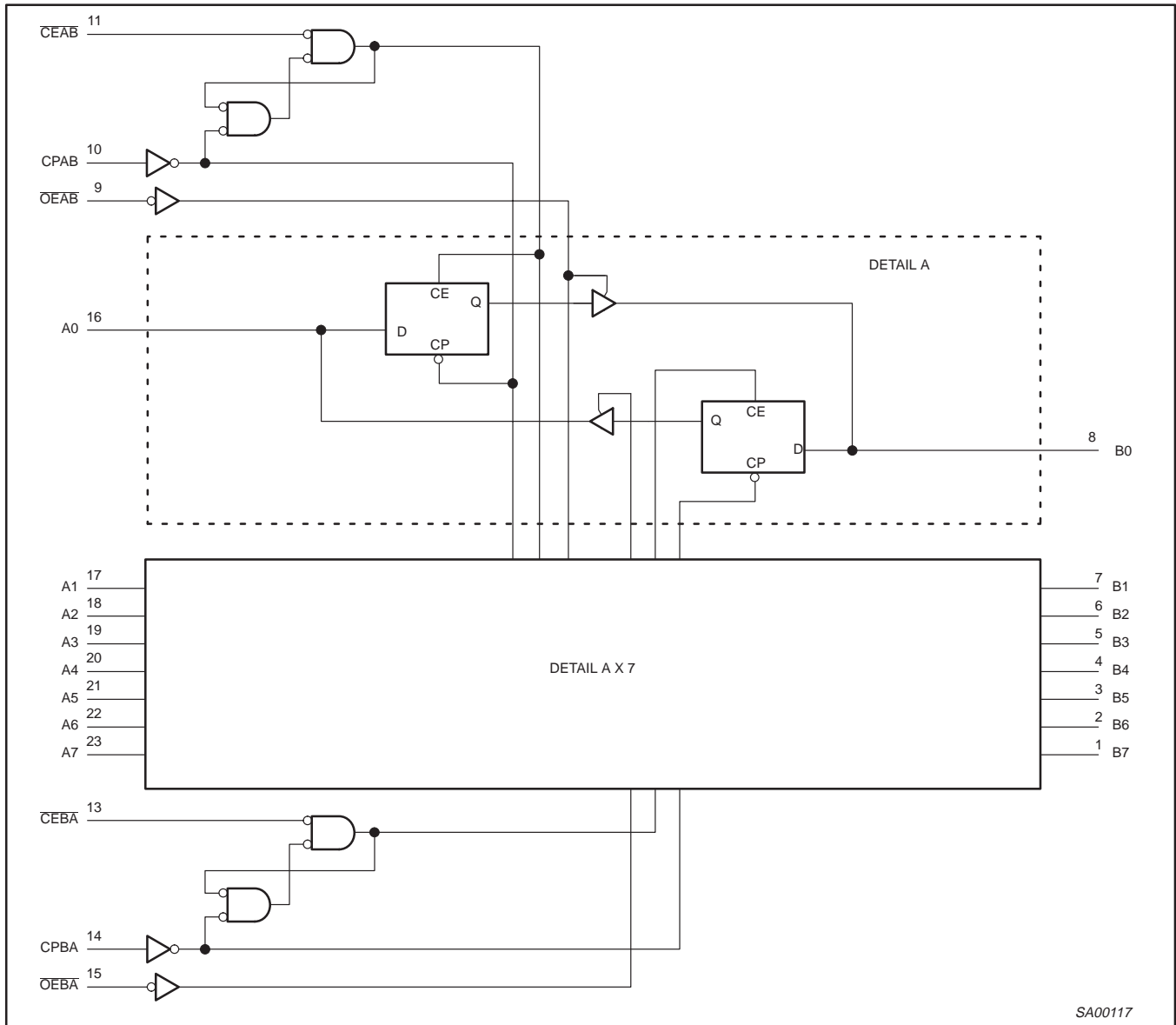
### NOTES:

- Stresses beyond those listed may cause permanent damage to the device. These are stress ratings only and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
- The performance capability of a high-performance integrated circuit in conjunction with its thermal environment can create junction temperatures which are detrimental to reliability. The maximum junction temperature of this integrated circuit should not exceed 150°C.
- The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

# Octal registered transceiver (3-State)

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## LOGIC DIAGRAM



SA00117

## RECOMMENDED OPERATING CONDITIONS

SYMBOL	PARAMETER	LIMITS		UNIT
		Min	Max	
V <sub>CC</sub>	DC supply voltage	4.5	5.5	V
V <sub>I</sub>	Input voltage	0	V <sub>CC</sub>	V
V <sub>IH</sub>	High-level input voltage	2.0		V
V <sub>IL</sub>	Low-level Input voltage		0.8	V
I <sub>OH</sub>	High-level output current		-32	mA
I <sub>OL</sub>	Low-level output current		64	mA
Δt/Δv	Input transition rise or fall rate	0	10	ns/V
T <sub>amb</sub>	Operating free-air temperature range	-40	+85	°C

## Octal registered transceiver (3-State)

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## DC ELECTRICAL CHARACTERISTICS

SYMBOL	PARAMETER		TEST CONDITIONS	LIMITS					UNIT
				T <sub>amb</sub> = +25°C			T <sub>amb</sub> = -40°C to +85°C		
				Min	Typ	Max	Min	Max	
V <sub>IK</sub>	Input clamp voltage		V <sub>CC</sub> = 4.5V; I <sub>IK</sub> = -18mA		-0.9	-1.2		-1.2	V
V <sub>OH</sub>	High-level output voltage		V <sub>CC</sub> = 4.5V; I <sub>OH</sub> = -3mA; V <sub>I</sub> = V <sub>IL</sub> or V <sub>IH</sub>	2.5	3.5		2.5		V
			V <sub>CC</sub> = 5.0V; I <sub>OH</sub> = -3mA; V <sub>I</sub> = V <sub>IL</sub> or V <sub>IH</sub>	3.0	4.0		3.0		V
			V <sub>CC</sub> = 4.5V; I <sub>OH</sub> = -32mA; V <sub>I</sub> = V <sub>IL</sub> or V <sub>IH</sub>	2.0	2.6		2.0		V
V <sub>OL</sub>	Low-level output voltage		V <sub>CC</sub> = 4.5V; I <sub>OL</sub> = 64mA; V <sub>I</sub> = V <sub>IL</sub> or V <sub>IH</sub>		0.42	0.55		0.55	V
V <sub>RST</sub>	Power-up output low voltage <sup>3</sup>		V <sub>CC</sub> = 5.5V; I <sub>O</sub> = 1mA; V <sub>I</sub> = GND or V <sub>CC</sub>		0.13	0.55		0.55	V
I <sub>I</sub>	Input leakage current	Control pins	V <sub>CC</sub> = 5.5V; V <sub>I</sub> = GND or 5.5V		±0.01	±1.0		±1.0	µA
		Data pins	V <sub>CC</sub> = 5.5V; V <sub>I</sub> = GND or 5.5V		5	100		100	µA
I <sub>OFF</sub>	Power-off leakage current		V <sub>CC</sub> = 0.0V; V <sub>O</sub> = 4.5V; V <sub>I</sub> = 0.0V or 5.5V		±5.0	±100		±100	µA
I <sub>PU</sub> /I <sub>PD</sub>	Power-up/down 3-State output current <sup>4</sup>		V <sub>CC</sub> = 2.1V; V <sub>O</sub> = 0.5V; V <sub>I</sub> = GND or V <sub>CC</sub> ; V <sub>OE</sub> = Don't care		±5.0	±50		±50	µA
I <sub>OZH</sub>	3-State output High current		V <sub>CC</sub> = 5.5V; V <sub>O</sub> = 2.7V; V <sub>I</sub> = V <sub>IL</sub> or V <sub>IH</sub>		5.0	50		50	µA
I <sub>OZL</sub>	3-State output Low current		V <sub>CC</sub> = 5.5V; V <sub>O</sub> = 0.5V; V <sub>I</sub> = V <sub>IL</sub> or V <sub>IH</sub>		-5.0	-50		-50	µA
I <sub>CEx</sub>	Output High leakage current		V <sub>CC</sub> = 5.5V; V <sub>O</sub> = 5.5V; V <sub>I</sub> = GND or V <sub>CC</sub>		5.0	50		50	µA
I <sub>O</sub>	Output current <sup>1</sup>		V <sub>CC</sub> = 5.5V; V <sub>O</sub> = 2.5V	-50	-80	-180	-50	-180	mA
I <sub>CCH</sub>	Quiescent supply current		V <sub>CC</sub> = 5.5V; Outputs High, V <sub>I</sub> = GND or V <sub>CC</sub>		110	250		250	µA
I <sub>CCL</sub>			V <sub>CC</sub> = 5.5V; Outputs Low, V <sub>I</sub> = GND or V <sub>CC</sub>		20	30		30	mA
I <sub>CCZ</sub>			V <sub>CC</sub> = 5.5V; Outputs 3-State; V <sub>I</sub> = GND or V <sub>CC</sub>		110	250		250	µA
ΔI <sub>CC</sub>	Additional supply current per input pin <sup>2</sup>		V <sub>CC</sub> = 5.5V; one input at 3.4V, other inputs at V <sub>CC</sub> or GND		0.3	1.5		1.5	mA

## NOTES:

- Not more than one output should be tested at a time, and the duration of the test should not exceed one second.
- This is the increase in supply current for each input at 3.4V.
- For valid test results, data must not be loaded into the flip-flops (or latches) after applying the power.
- This parameter is valid for any V<sub>CC</sub> between 0V and 2.1V, with a transition time of up to 10msec. From V<sub>CC</sub> = 2.1V to V<sub>CC</sub> = 5V ± 10% a transition time of up to 100µsec is permitted.

## AC CHARACTERISTICS

GND = 0V; t<sub>R</sub> = t<sub>F</sub> = 2.5ns; C<sub>L</sub> = 50pF, R<sub>L</sub> = 500Ω

SYMBOL	PARAMETER	WAVEFORM	LIMITS					UNIT
			T <sub>amb</sub> = +25°C V <sub>CC</sub> = +5.0V			T <sub>amb</sub> = -40°C to +85°C V <sub>CC</sub> = +5.0V ±0.5V		
			Min	Typ	Max	Min	Max	
f <sub>MAX</sub>	Maximum clock frequency	1	150	250		150		MHz
t <sub>PLH</sub> t <sub>PHL</sub>	Propagation delay CPBA to An, CPAB to Bn	1	2.0 2.5	3.2 3.8	6.6 7.2	2.0 2.5	7.6 8.2	ns
t <sub>PZH</sub> t <sub>PZL</sub>	Output enable time OEBA to An, OEAB to Bn	3 4	1.0 2.2	3.2 4.4	4.8 6.2	1.0 2.2	5.8 7.5	ns
t <sub>PHZ</sub> t <sub>PLZ</sub>	Output disable time OEBA to An, OEAB to Bn	3 4	2.0 1.5	3.6 2.8	7.6 7.1	2.0 1.5	8.1 7.6	ns

# Octal registered transceiver (3-State)

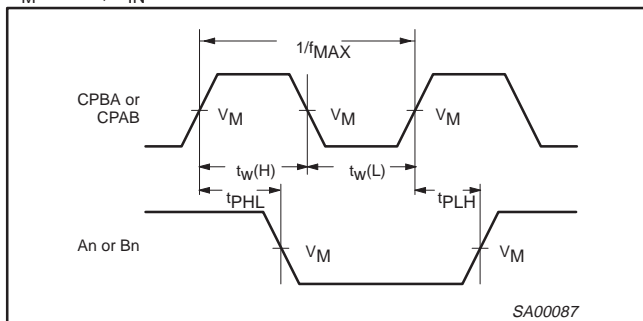
74ABT2952

## AC SETUP REQUIREMENTS

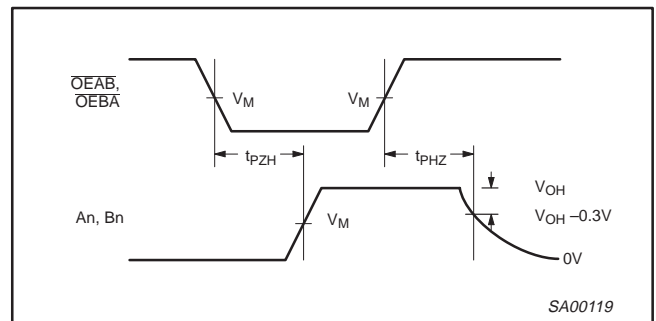
SYMBOL	PARAMETER	WAVEFORM	LIMITS			UNIT
			$T_{amb} = +25^{\circ}C$ $V_{CC} = +5.0V$		$T_{amb} = -40^{\circ}C$ to $+85^{\circ}C$ $V_{CC} = +5.0V \pm 0.5V$	
			Min	Typ	Min	
$t_s(H)$ $t_s(L)$	Setup time An to CPAB or Bn to CPBA	2	4.5 3.5	2.2 1.6	4.5 3.5	ns
$t_h(H)$ $t_h(L)$	Hold time An to CPAB or Bn to CPBA	2	0.0 0.0	-0.8 -1.4	0.0 0.0	ns
$t_s(H)$ $t_s(L)$	Setup time $\overline{CEAB}$ to CPAB, $\overline{CEBA}$ to CPBA	2	4.0 3.0	0.8 0.8	4.0 3.0	ns
$t_h(H)$ $t_h(L)$	Hold time $\overline{CEAB}$ to CPAB, $\overline{CEBA}$ to CPBA	2	0.0 0.0	-0.7 -0.7	0.0 0.0	ns
$t_w(H)$ $t_w(L)$	CPAB or CPBA pulse width, High or Low	1	3.0 3.5	0.8 0.9	3.0 3.5	ns

## AC WAVEFORMS

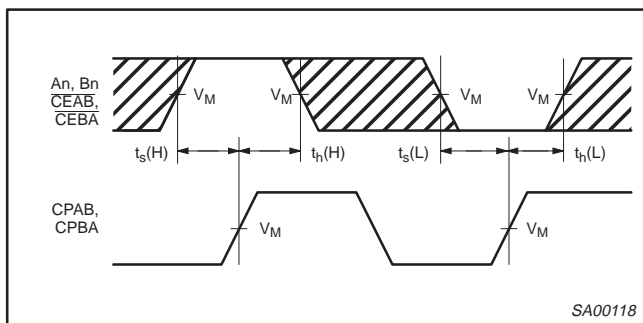
$V_M = 1.5V$ ,  $V_{IN} = GND$  to  $3.0V$



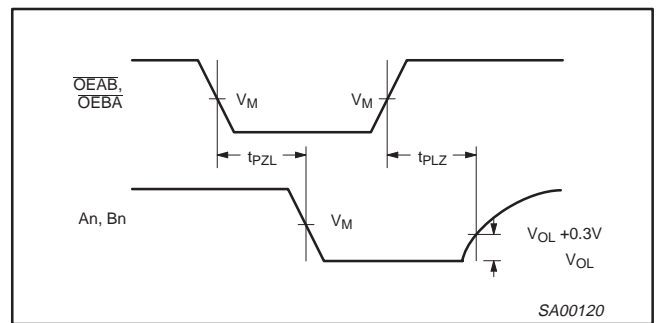
**Waveform 1. Propagation Delay, Clock Input to Output, Clock Pulse Width, and Maximum Clock Frequency**



**Waveform 3. 3-State Output Enable Time to High Level and Output Disable Time from High Level**



**Waveform 2. Data Setup and Hold Times**

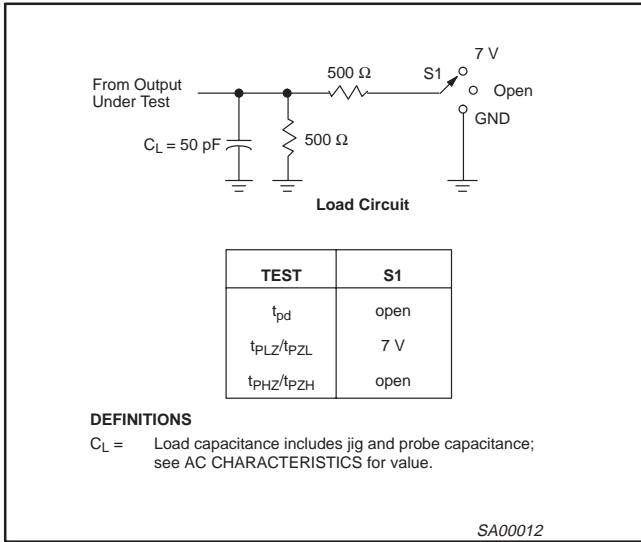


**Waveform 4. 3-State Output Enable Time to Low Level and Output Disable Time from Low Level**

## TEST CIRCUIT AND WAVEFORMS

# Octal registered transceiver (3-State)

## 74ABT2952

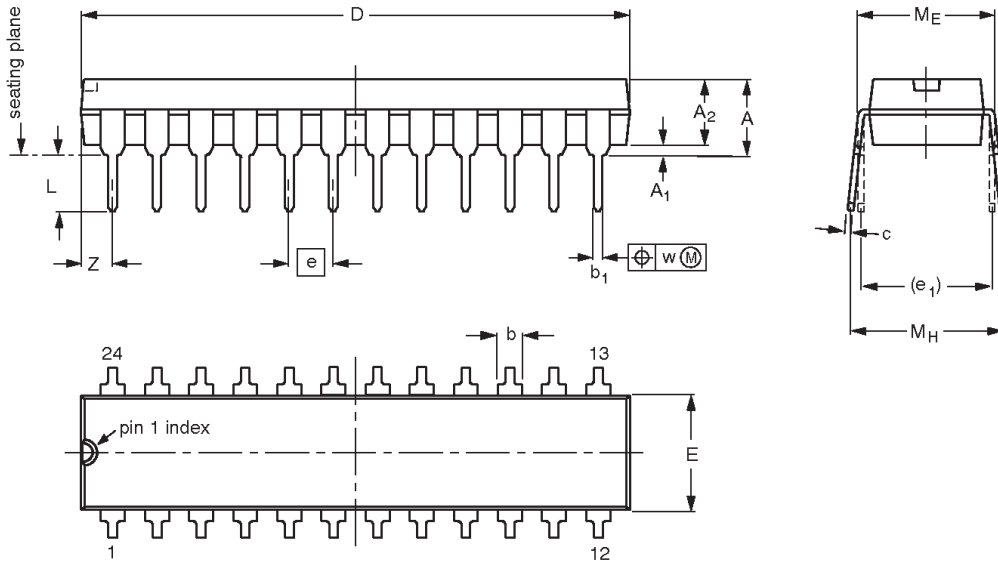


# Octal registered transceiver (3-State)

## 74ABT2952

DIP24: plastic dual in-line package; 24 leads (300 mil)

SOT222-1



**DIMENSIONS (millimetre dimensions are derived from the original inch dimensions)**

UNIT	A max.	A <sub>1</sub> min.	A <sub>2</sub> max.	b	b <sub>1</sub>	c	D <sup>(1)</sup>	E <sup>(1)</sup>	e	e <sub>1</sub>	L	M <sub>E</sub>	M <sub>H</sub>	w	Z <sup>(1)</sup> max.
mm	4.70	0.38	3.94	1.63 1.14	0.56 0.43	0.36 0.25	31.9 31.5	6.73 6.48	2.54	7.62	3.51 3.05	8.13 7.62	10.03 7.62	0.25	2.05
inches	0.185	0.015	0.155	0.064 0.045	0.022 0.017	0.014 0.010	1.256 1.240	0.265 0.255	0.100	0.300	0.138 0.120	0.32 0.30	0.395 0.300	0.01	0.081

**Note**

1. Plastic or metal protrusions of 0.01 inches maximum per side are not included.

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	EIAJ			
SOT222-1		MS-001AF				95-03-11

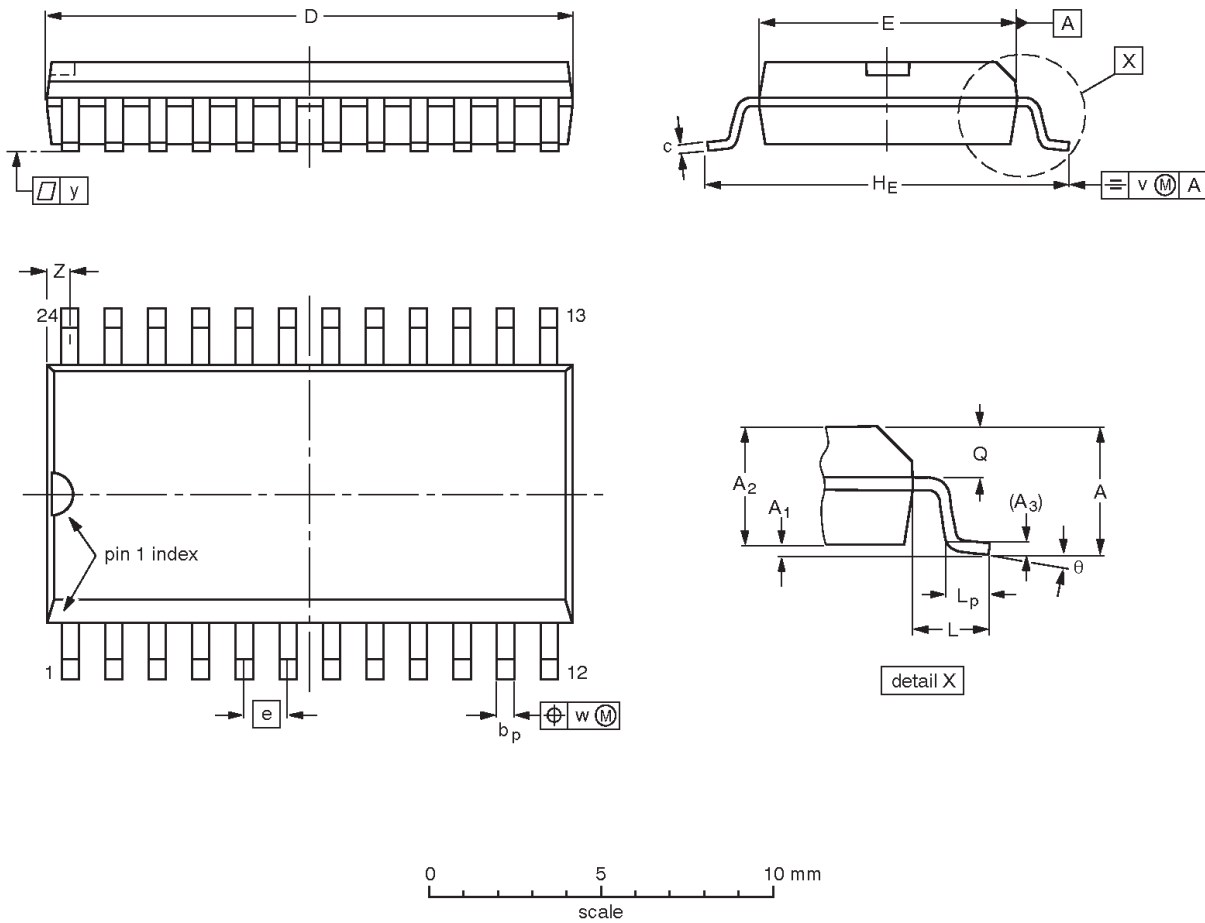


# Octal registered transceiver (3-State)

# 74ABT2952

**SO24:** plastic small outline package; 24 leads; body width 7.5 mm

**SOT137-1**



**DIMENSIONS (inch dimensions are derived from the original mm dimensions)**

UNIT	A max.	A <sub>1</sub>	A <sub>2</sub>	A <sub>3</sub>	b <sub>p</sub>	c	D <sup>(1)</sup>	E <sup>(1)</sup>	e	H <sub>E</sub>	L	L <sub>p</sub>	Q	v	w	y	z <sup>(1)</sup>	θ
mm	2.65	0.30 0.10	2.45 2.25	0.25	0.49 0.36	0.32 0.23	15.6 15.2	7.6 7.4	1.27	10.65 10.00	1.4	1.1 0.4	1.1 1.0	0.25	0.25	0.1	0.9 0.4	8° 0°
inches	0.10	0.012 0.004	0.096 0.089	0.01	0.019 0.014	0.013 0.009	0.61 0.60	0.30 0.29	0.050	0.419 0.394	0.055	0.043 0.016	0.043 0.039	0.01	0.01	0.004	0.035 0.016	

**Note**

1. Plastic or metal protrusions of 0.15 mm maximum per side are not included.

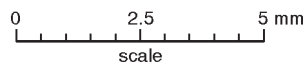
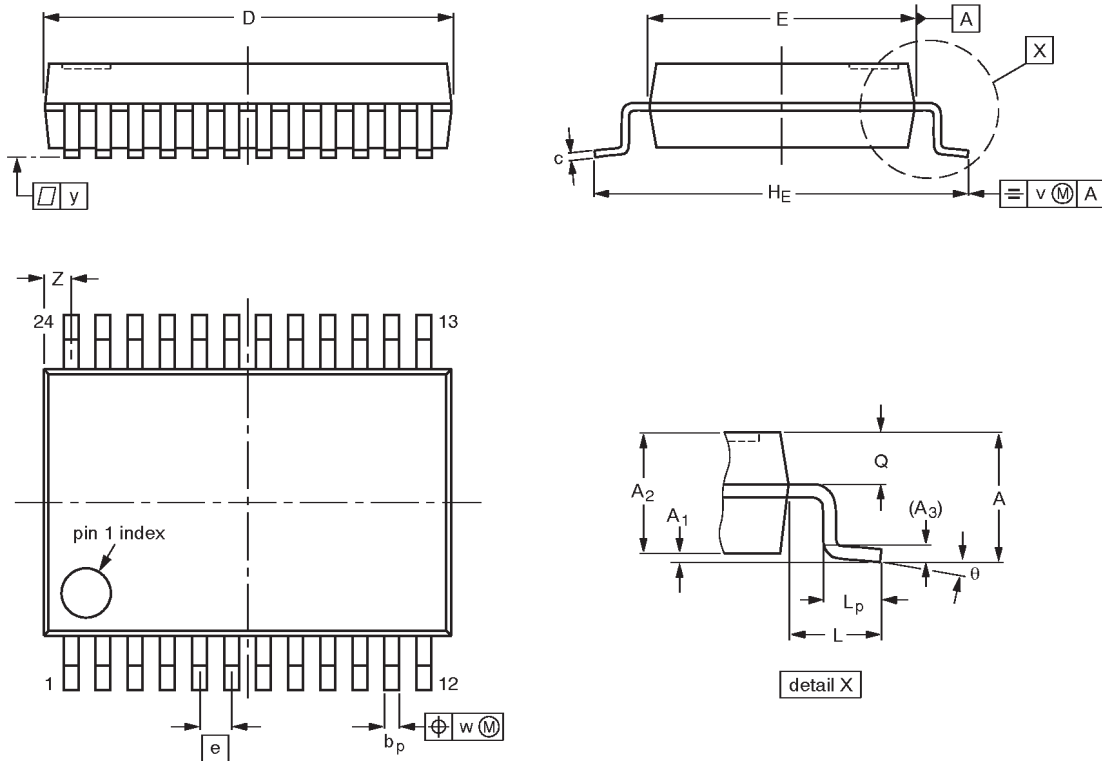
OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	EIAJ			
SOT137-1	075E05	MS-013AD				-95-01-24 97-05-22

# Octal registered transceiver (3-State)

# 74ABT2952

**SSOP24:** plastic shrink small outline package; 24 leads; body width 5.3 mm

**SOT340-1**



**DIMENSIONS (mm are the original dimensions)**

UNIT	A max.	A <sub>1</sub>	A <sub>2</sub>	A <sub>3</sub>	b <sub>p</sub>	c	D <sup>(1)</sup>	E <sup>(1)</sup>	e	H <sub>E</sub>	L	L <sub>p</sub>	Q	v	w	y	z <sup>(1)</sup>	θ
mm	2.0	0.21 0.05	1.80 1.65	0.25	0.38 0.25	0.20 0.09	8.4 8.0	5.4 5.2	0.65	7.9 7.6	1.25	1.03 0.63	0.9 0.7	0.2	0.13	0.1	0.8 0.4	8° 0°

**Note**

1. Plastic or metal protrusions of 0.20 mm maximum per side are not included.

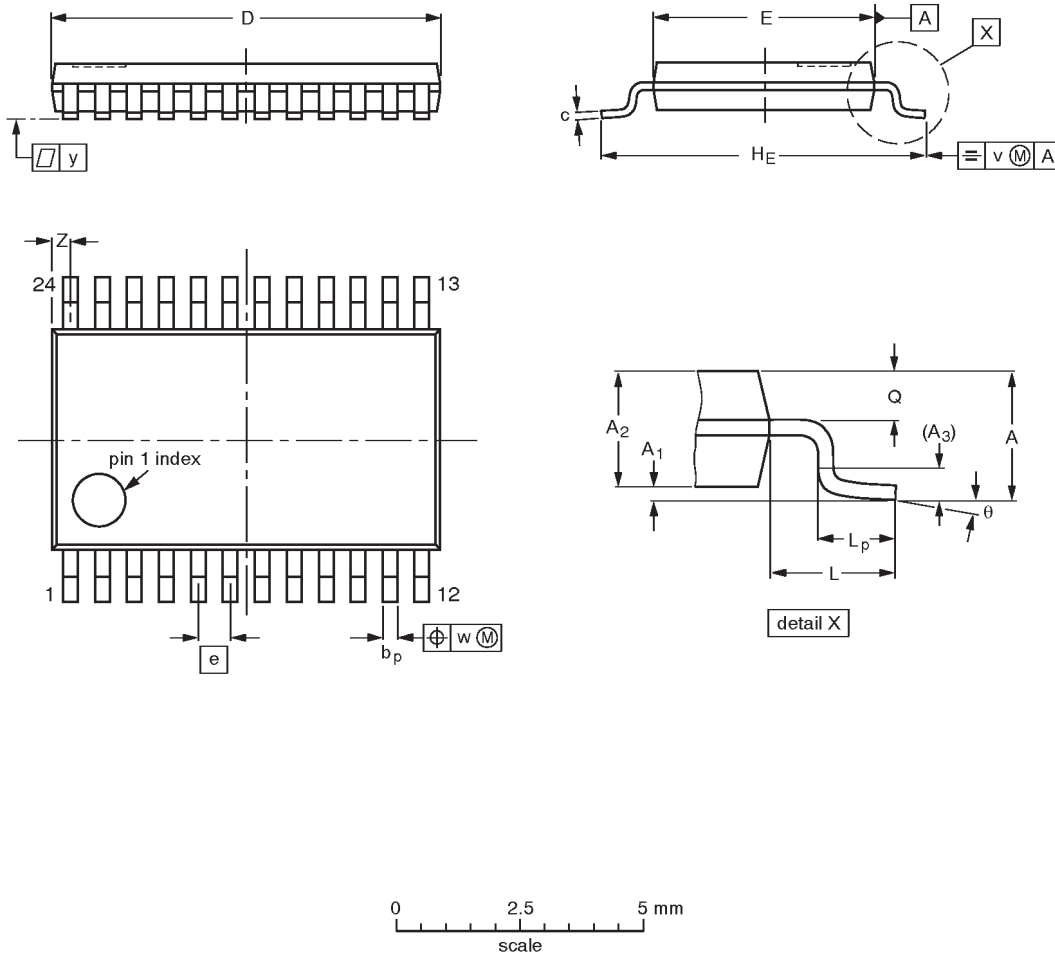
OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	EIAJ			
SOT340-1		MO-150AG				93-09-08 95-02-04

# Octal registered transceiver (3-State)

# 74ABT2952

**TSSOP24:** plastic thin shrink small outline package; 24 leads; body width 4.4 mm

**SOT355-1**



**DIMENSIONS (mm are the original dimensions)**

UNIT	A max.	A <sub>1</sub>	A <sub>2</sub>	A <sub>3</sub>	b <sub>p</sub>	c	D <sup>(1)</sup>	E <sup>(2)</sup>	e	H <sub>E</sub>	L	L <sub>p</sub>	Q	v	w	y	Z <sup>(1)</sup>	θ
mm	1.10	0.15 0.05	0.95 0.80	0.25	0.30 0.19	0.2 0.1	7.9 7.7	4.5 4.3	0.65	6.6 6.2	1.0	0.75 0.50	0.4 0.3	0.2	0.13	0.1	0.5 0.2	8° 0°

**Notes**

1. Plastic or metal protrusions of 0.15 mm maximum per side are not included.
2. Plastic interlead protrusions of 0.25 mm maximum per side are not included.

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	EIAJ			
SOT355-1		MO-153AD				-93-06-16 95-02-04

## Octal registered transceiver (3-State)

74ABT2952

## Data sheet status

Data sheet status	Product status	Definition [1]
Objective specification	Development	This data sheet contains the design target or goal specifications for product development. Specification may change in any manner without notice.
Preliminary specification	Qualification	This data sheet contains preliminary data, and supplementary data will be published at a later date. Philips Semiconductors reserves the right to make changes at any time without notice in order to improve design and supply the best possible product.
Product specification	Production	This data sheet contains final specifications. Philips Semiconductors reserves the right to make changes at any time without notice in order to improve design and supply the best possible product.

[1] Please consult the most recently issued datasheet before initiating or completing a design.

## Definitions

**Short-form specification** — The data in a short-form specification is extracted from a full data sheet with the same type number and title. For detailed information see the relevant data sheet or data handbook.

**Limiting values definition** — Limiting values given are in accordance with the Absolute Maximum Rating System (IEC 134). Stress above one or more of the limiting values may cause permanent damage to the device. These are stress ratings only and operation of the device at these or at any other conditions above those given in the Characteristics sections of the specification is not implied. Exposure to limiting values for extended periods may affect device reliability.

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Philips Semiconductors  
811 East Arques Avenue  
P.O. Box 3409  
Sunnyvale, California 94088-3409  
Telephone 800-234-7381

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